L Number	Hits	Search Text	DB	Time stamp
1	12	(gerald near2 friese).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 14:19
-	2	20020016070.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:45
-	4	6159826.pn. or 6239494.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:46
-	1987	bond near2 pad same (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 14:47
-	60	bond near2 pad same (copper or cu) same probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:03
-	56	bond$3 near2 pad same probe same barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:07
-	4175	bond$3 near2 pad near10 structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:07
-	194	bond$3 near2 pad near10 structure same probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:08
-	43	bond$3 near2 pad near10 structure same probe near2 (region or pad or area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:08
-	110	bond$3 near2 pad near10 structure near20 probe near2 (region or pad or area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:08
-	109	bond$3 near2 pad near10 structure near15 probe near2 (region or pad or area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:15
-	3	"03003458"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:15
-	6	"3003458"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 15:16
-	1	6600226.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:15

-	120	diffus$4 near4 barrier near10 bond$4 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:15
-	31	diffus$4 near4 barrier near10 bond$4 near2 pad near10 (via or trench or inter$1connect$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:36
-	5	diffus$4 near4 barrier near10 bond$4 near2 pad near10 probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:37
-	1308	bond$4 near2 pad near10 probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:37
-	1295	bond$4 near2 pad near10 probe near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:38
-	17	bond$4 near2 pad near10 probe near2 pad near10 etch$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:58
-	41	oxide near2 dielectric near4 (boron or phosphorous) near3 dop$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/10 16:58
-	1410	passivat$4 near2 layer near10 bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:53
-	380	passivat$4 near2 layer near10 bond$3 near2 pad near10 etch$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:54
-	11	passivat$4 near2 layer near10 bond$3 near2 pad near10 etch$4 near10 prob$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:56
-	1825	bond$3 near2 pad near10 thick$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:57
-	232	bond$3 near2 pad near10 thick$4 near10 (al or aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:57
-	147	bond$3 near2 pad near5 thick$4 near10 (al or aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:57
-	55	bond$3 near2 pad near2 thick$4 near10 (al or aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 13:57

-	4	(al or aluminum) near2 (bond$3 near2 pad) same (copper or cu) near4 (line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:27
-	566	barrier near2 metal near10 (tin titanium or tungsten) near(tan or ta or tantalum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:28
-	1	barrier near2 metal near10 (tin titanium or tungsten) near2 (tan or ta or tantalum) near10 (bond$3 near2 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:29
-	1	barrier near2 metal near10 (tin titanium or tungsten) near2 (tan or ta or tantalum) near20 (bond$3 near2 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:57
-	1	barrier near2 metal near10 (tin titanium or tungsten) near10 (tan or ta or tantalum) near20 (bond$3 near2 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:58
-	3	barrier near2 metal near10 (tin titanium or tungsten) near10 (tan or ta or tantalum) near20 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:59
-	828	barrier near2 metal near10 (tin titanium or tungsten) near10 (tan or ta or tantalum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 15:59
-	118	barrier near2 metal near10 (tin titanium or tungsten) near10 (tan or ta or tantalum) near10 (diffus$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:02
-	1	barrier near2 metal near10 (tin titanium or tungsten) near10 (tan or ta or tantalum) near10 (diffus$) and bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:03
-	6330	dielectric near2 defin$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:03
-	373	dielectric near2 defin$5 near10 insulat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:04
-	181	dielectric near2 defin$5 near10 insulat$4 and @py<2000	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:25
-	10	(copper or cu) near10 metal near2 line near20 bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:29
-	81	(copper or cu) near10 line near20 bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:33

-	228	(copper or cu) near10 line near5 metal$5 and bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 16:44
-	2	5785236.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:11
-	287	(aluminum or al) near5 interconnect$4 near20 bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:12
-	150	(aluminum or al) near2 interconnect$4 near20 bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:12
-	2	(aluminum or al) near2 interconnect$4 near20 bond$3 near2 pad near4 (aluminum or al) near20 (copper or cu) near4 line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:12
-	113	(aluminum or al) near2 interconnect$4 near20 bond$3 near2 pad near4 (aluminum or al)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:13
-	3410	(copper or cu) near10 refract$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:27
-	56	(copper or cu) near10 refract$4 near5 line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:29
-	2732	conduct$5 near5 line near10 (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:29
-	1658	conduct$5 near2 line near10 (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:29
-	221	conduct$5 near2 line near10 (copper or cu) near10 circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:29
-	5	conduct$5 near2 line near10 (copper or cu) near10 circuit same bond$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:30
-	176	conduct$5 near2 line near5 (copper or cu) near10 circuit and py<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/11 17:31
-	101	conduct$5 near2 line near5 (copper or cu) near10 circuit and @py<2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:28

-	6347	bond near2 pad near5 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:28
-	1445	bond near2 pad near5 wire near10 device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:28
-	65	bond near2 pad near5 wire near10 device near5 (al or aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:30
-	1	bond near2 pad near5 wire near10 device near5 permanent$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:30
-	19	bond near2 pad near5 wire near10 permanent$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:35
-	16	bond near2 pad near10 bond near2 wire near10 permanent$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:37
-	19	bond near2 pad near10 wire near10 permanent$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:46
-	1621	barrier near2 layer near5 (titanium ti tin) near5 (tantalum or tan or ta)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:47
-	0	barrier near2 layer near5 (titanium ti tin) near5 (tantalum or tan or ta) near10 bond near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:47
-	0	barrier near2 layer near5 (titanium ti tin) near5 (tantalum or tan or ta) near20 bond near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:47
-	52	barrier near2 layer near5 (titanium ti tin) near5 (tantalum or tan or ta) near5 (copper and aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/12 10:47